Westmere Xeon-56xx "Tick" CPU

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Intel Oregon



Hot Chips 2010

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Westmere Xeon-56xx



Agenda

- The "Tick" Challenge at Intel
- Westmere Xeon-56xx (EP) : 1000 Foot View
- Xeon-56xx Architectural Focus areas :
 - Performance Scalability
 - Virtualization
 - Security
 - Power-Efficiency

Note : Westmere Xeon-56xx presentation material today, performance measurement data, and described product SKU's are based on shipping products.



Intel Tick-Tock background

Merom	Penryn	Nehalem	Westmere	Sandy Bridge
NEW	NEW	NEW	NEW	NEW
Microarchitectur	Process	Microarchitectur	Process	Microarchitectur
65nm	45nm	45nm	32nm	ء 32nm
TOCK	TICK	ТОСК	TICK	ТОСК
		Shipping		

- "Tock-Tick" Pairs tightly coupled leverage of oneanother
- Tocks introduce major platform changes and architectural themes
 - on a mature process
- Ticks introduce the new Process capabilities
 - advancing a mature Tock architecture



WSM-56xx Design Challenges

Ticks are developed in a constrained environment

- Timeline: Shorter design cycle based on TTM (don't holdup FAB)
- Process Stability: New process means Design Development is concurrent with Process fine-tuning. On the fly adjustments.
 - Example : moving tock design to new process creates some different speedpaths, circuits that behave differently than last process. Risk of new tick process at beginning of life being slower than the more mature tock process. Takes back-forth work between Design, Process, Arch to find balance.
- Design Data-Base Leverage from Tock :
 - Maximize Leverage of existing Design database inherited from tock
 - Typical reuse goal of at least 60% of tock RTL. WSM was a little higher.
 - Reuse available at transistor/layout level, not just RTL & tests
 - Innovations have to be non-disruptive to the inherited DB, form-factor
 - Not just an Intel thing.. All OEM re-validation risk and effort benefits from leveraging as much as possible in a "drop in" approach to the tick.

Challenge: Deliver Compelling Goodness despite constraints



Westmere 56xx – What is it ?

263mm



45nm Nehalem (55xx series)

- 32nm ~drop-in compatible to NHM 55xx spec compliant UP and DP platforms. 1366 pins (600+ Power/Vss) socket-B same as NHM.
- Conceptually simple :
- +50% cores (6)
- +50% L3 cache(12MB)
- -10% area (239mm)
- similar total power and thermal characteristics to four core NHM it replaces Converged Core Architecture

239mm



32nm Westmere (56xx series)



WSM-56xx Focus Areas

- Platform Compatible. Straightforward Scalability
 - Leverage 32nm process to grow Core-Count, L3 Cache 50%
 - Ease new product transition pain and risk for customers.
- Power Performance
 - Leverage 32nm process as more performance at similar power envelope, OR similar performance at lower power levels.
- Security
 - A step forward. HW assist AES Encrypt/Decrypt. TXT extensions
- Virtualization
 - Key Datacenter ask : Boost Virtualization performance
- Over 100 additional incremental improvements
 - Customer feedback requests and incremental improvements from tock learnings fill out net team execution bandwidth available (top-10 next page)



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Westmere 56xx – Top 10 Improvements

- Added 50% cores, 50% L3 cache- within NHM platform constraints.
- Memory Support
 - 1.5v DDR3, plus new LV-DDR3 support (1.35v for better platform power)
 - 2 DIMM per channel @ 1333 DDR3 (NHM 2DPC support up to 1067)
- More peak CPU and I/O Bandwidth to memory
 - 64 → 88 uncore buffer depth increase per socket for supporting more transactions to DDR in flight.
- AES-NI 7 new instructions
 - Benefits encrypt / decrypt standard used for securing web and storage information
- TXT (trusted execution)
 - Measured Launch Environment to harden platforms from hypervisor, bios, rootkit attacks.
- Improved Virtualization
 - Real-mode support, Lower transition latencies vs NHM
- 1 GBpage table entries
 - Support for larger page size (for multi GByte High Performance Computing memory footprints)
- PCID
 - Tag TLB entries with process context ID so they may persist across CR3 writes
 - Similar to VPID functionality added in NHM, but in non-Virtualized format
- Two more MTRR's (10 variable memory type range registers)
 - Overdue help for BIOS code setup of memory type regions
- Always running Apic Timer
 - resolves prior art documented apic-timer drift/timewarp issue during power modes where core was off.



Performance Scalability

How it was done, and Results



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How was it done ?



32nm Westmere (56xx series)

- Pre-plumb NHM platforms for 32nm
 - example : 32nm uses slightly different Core, UnCore and I/O voltages than 45nm. NHM spec'ed the voltage regulators, voltage range selection interface and current requirements to cover 45nm, and 32nm Westmere needs.
- Architect NHM with Uncore, QPI, DDR headroom
 - Cache tag bandwidth, IDI, PCU, QPI built to survive tick scaling needs.
- Upfront work w/Manufacturing to tune process
 - Lots of work getting transistor characteristics, cell library, metal pitch, etc to enable best transition of tock design to the new tick process.
- Core team builds 32nm WSM core database (AES etc)
- UnCore team extends buffered cross-bar to 6-core plumbing
 - Slide 4-cores away from Uncore
 - Insert cores 5,6 & add core-uncore IDI domain-jump connections
 - Find and extend many 2-bit fields to 3 bits
- Extend to 12MB L3 cache, XSnp-filers, PCU to 6core, schedulers, etc
 - L3 still 16-way shared. SET address arithmetic changed.
- Add a clock each direction to IDI,L3\$, QPI, DDR paths for increased effective physical distances involved (simple RC issue).
- Repartition and bolster buffering.
 - Bumped 64→88 max DDR requests per socket.
- Resolve and validate the many details
- Backend work w/Manufacturing to tune process and sorting
 - Attain freq and power characteristic goals of the "drop in" paradigm.
 - Parts are sorted and fused at test time to best voltage and frequency bins.
 - Above is key... no one voltage at which WSM parts run



Scaling Results : Xeon[®] 5500 → Xeon[®] 56xx

Left-Side = 4Core Nehalem 55xx Parts Right-Side = Westmere 56xx Parts

Xeon[®] 56xx



Intel[®] Xeon[®] Processor 56xx Series Measured Silicon System Performance Summary



Up to 63% performance boost over Xeon[®] 5500 Sources : Core count, Cache size, 2-bins of Frequency

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14 Source: Intel Internal measurements March 30, 2010.

Security

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AES-NI – why not a CISC operation?

- AES defines 3 different key sizes:
 - 128/192/256 bit
 - Which take 10/12/14 algorithm calculation rounds respectively
- AES has a large number of modes (ECB, CBC, CTR, GCM, XTS, XTW, etc.)
- Could have built a single CISC instruction to do AES encrypt/decrypt :
 - Severely complicated flow. Potential export implications.
 - Might have picked the wrong modes, key sizes, etc.
- Split the AES operations into components
 - Forward cipher: AESENC, AESENCLST
 - Equivalent Inverse Cipher: AESDEC, AESDECLST
 - Key generation, matrix manipulation: AESIMC and AESKEYGENASST
 - Carryless multiply : CLMUL

AESNI Whitepaper at Intel.com (see last foil)



AES Encryption Flow



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AES-NI Perf

openssl –speed –evp aes-128-cbc cycles/ byte measured on WSM 1C/ 1T

- Up to 8x cycles/byte raw improvement
 OpenSSL Secure Socket Layer 1.0.0
- Execute with SSE operations:
 - AES at 16-bytes is natural fit for SSE HW.
 - Side-channel hardened (meaning operation timing / cache behavior is independent of secrets being protected).
- Enabled SW (BitLocker*, PGP*, TrueCrypt*, WinZip* ...) seeing significant benefits (next foil)



- OpenSSL 1.0.0 is "side-channel" hardened, so it is the appropriate comparison. SSL is Secure Socket Layer used for internet communication.
- 0.9.8 is shown for completeness
- CBC Encrypt is representative of a "serial" cipher mode. CBC Decrypt is representative of a "parallel" cipher mode. SW does not achieve pipelining in the decrypt case like the hardware.



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Intel® Xeon® 56xx Series AES Encryption Performance



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- 1 Windows 2008 R2 x64 Enterprise Server. PHP banking sessions /users measured with Intel® Xeon® X5680 processor (WSM, 3.33 GHz) vs Inel® Xeon® 5160 processor (Woodcrest, 3 GHz) and Intel® Xeon® X5570 processor (NHM, 2.93 GHz), 24 SSD RAID 0 arrays, TLS_RSA_with_AES_128_CBC_SHA cipher suite.
- Oracle 11g with TDE, time takes to decrypt a 5.1 million row encrypted table with AES-256 CBC mode on Intel® Xeon® X5680 processor (WSM, 3.33 GHz) optimized with Intel® Performance Primitives crypto library (IPP) vs Intel® Xeon® X5560 processor (NHM, 2.8 GHz) without IPP. Timing measured is per 4K of data.
- ³ McAfee Endpoint Encryption for PCs (EEPC) 6.0 package with McAfee ePolicy Orchestrator (ePO) 4.5 encrypting a 32GB X25E SSD with Intel® Xeon® X5680 processor (WSM, 3.33 GHz) vs. Intel® Xeon® X5570 (NHM, 2.93 GHz). 24GB of memory.



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Virtualization

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VT-x Improvements

- VT-x transition latency reduction:
 - Up to three VMCS's (virtual machine control structure) now cached in private SRAM on die.
 - Contains architectural state and VMX controls.
 - Previously cached only portions of the one currently active VMCS.
- VMX Architecture Enhancement "Unrestricted Guest" Mode
 - Allows VM guests to be in Real-Mode and unpaged protected mode.
 - Removes the need for a Real-Mode interpreter in VMM.
 - Significant boot time reductions for certain guests.



Relative VT-x transition latency

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Intel® Xeon® Processor 56xx series based Server platforms Virtualization performance on VMware ESX* using VMmark* benchmark



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Power Efficiency Summary

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- 32nm Process and Scalable Architecture Enabled :
 - 50% more cores, 50% more L3 cache
 - Same or higher max frequencies as 45nm Nehalem cores
 - Similar to 4 core Nehalem power envelopes. 60w 95w
 - Similar Idle power
 - OR
 - 4 cores in lower power envelopes. 45nm 80w → 32nm 40w
- Key new features, and refinement of the NHM tock
 - Lower power DDR3L 1.35v dimm support
 - Higher peak memory bandwidth and 2DPC @ 1333
 - AESNI and TXT Measured Launch Security improvements.
 - VTx latency and real-mode support improvements.



Intel[®] Xeon[®] Processor 56xx Series



Better Energy Efficiency

with same performance as X5570 and up to 30% lower power¹

Performance Leadership with up to 60% performance boost over Xeon[®] 5500 servers²

More Secure

with Intel[®] AES New Instructions and Intel[®] Trusted Execution Technology

Intel[®] 32nm Process

1 Source: Fujitsu Performance measurements comparing Xeon L5650 vs X5570 SKUs using SPECint_rate_base2006

2 Source: Internal Intel measurements for Xeon® X5680 va Xeon® X5570 on BlackScholes*

3 Source: Intel new Second Status C Fe 20X Geo Am D Conversion using server side java bops (business operations per second). Results have been estimated based on internal Intel analysis and are provided for informational purposes only.



25 For notes and disclaimers, see performance and legal information slides at end of this presentation.

Backup

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Westmere Xeon-56xx – Overview

Actively shipping

Westmere-56xx

Up to 6 core/12 Thread

12 MB shared L3 cache

3 channels of DDR3, 3L memory support

AES, TXT, Improved Virtualization support

Westmere-56xx Processor Intel 5500 & 520 Chipset

Socket: (same as NHM)• LGA 1366 Pin SocketProcess Technology:• 32nm CPUPlatform Compatibility:

• Intel® 5500 & 5520 Chipset

Power:

• 130W down to 40W

Adds 1.35v DDR3L

support

Socket & Pin Compatible with Xeon 5500 Platforms with Additional Cores, Cache and 32nm Enhancements

Westmere Xeon-56xx

QPI: Intel® QuickPath Interconnect (Intel® QPI)





Greater Datacenter Energy Efficiency



Maximize Performance or Energy Efficiency

¹ Source: Internal Intel estimates comparing Xeon® X5670 vs. X5570 SKUs using SPECpower. See backup for system configurations.

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Intel® Xeon® Processor 5600 series based Server platforms Energy Efficient performance on SPECpower* _ssj2008





- <u>Comparison basis:</u> X86 architecture based DP Server platforms
- Leading result by IBM on IBM System x 3650 M3 server platform on Xeon X5670
 - IBM J9* JVM
 - Microsoft Windows Server 2008 Enterprise*

Benchmark notes:

- Measures energy efficiency of volume servers
- First industry standard bmk to measure power consumption in relation to performance across a "graduated" workload (11 different load levels -100%, 90%, 80% down to 0%)
- Measures platform power AC watts at the wall
- Metric: Overall ssj_ops / watt (sum of the 11 perf points divided by sum of the 11 power points)

Xeon 5670 delivers all-time high SPECpower*_ssj2008 score

Xeon 3.60 – Intel® Xeon® Processor 3.60 1M L2 ("Nocona 3.60GHz", Single-Core) Xeon 5160 – Intel® Xeon® Processor 5160 ("Woodcreet 2.0GHz", Dual-Core) Xeon 5470 – Intel® Xeon® Processor L5430 ("Harpertown 2.56GHz", Quad-Core) Xeon 5570 – Intel® Xeon® Processor X5570 ("Nehalem-EP 2.93GHz", Quad-Core) Opteron 3435 – Six Core "Istanbul" Opteron 6174 – Magny Cour



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ISV Energy Efficiency Proof Points

	ISV	Market Segment & Application	Xeon 5600 vs. 5500 series
Giant*	6月1日日日日日日日日日日日日日日日日日日日日日日日日日日日日日日日日日日日日	Giant is the one of the biggest online game vendor in China. Juren online game is the newest game developed by Giant	+30%
IBM*	IBM Information Management software	IBM DB2 is a database Application. Hybrid data server for both XML and relational data	+29%
Kingsoft*		Kingsoft JXIII Online Game Server is next generation online game	+52%
Neusoft*	Neusoft	Neusoft CT &Pacs is key digital health solution focusing on X-ray computed tomography medical image processing	+37%
SAP*		The SAP ERP application (ECC 5.0) is an integrated software that addresses business requirements of mid and large orgs	+36%

Intel® Xeon® processor 5600 series delivers energy efficiency leadership with performance per Watt up to +52%

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Intel® Xeon® 5600 Performance Records*

*As of May 28, 2010

Benchmark	Percentage gain over Xe	eon 5500	Result published by
Vmmark*		42%	Cisco
•• Multi-node SPECpow	er* _ssj2008	42%	HP
•• TPC Benchmark* E		35%	HP
•• SPECjEnterprise* 2010 33%			IBM
··· Single-node SPECpo	33% IBM		
•• SPECjAppServer* 20)4	30%	Cisco
•• SAP-SD* 2-Tier			HP
•• SPECWeb* 2005		25%	Fujitsu
•• TPC Benchmark* C		21%	HP
•• SPEComp* Mbase200	1	20%	Cisco
•• SPECint* _base2006			10%

Fujitsu

Over <u>NINE</u> New x86 2S Server & Workstation World Records

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Seven AES Instructions

Round Instructions:

AESENC xmm, xmm/m128: Encrypt one round AESENCLAST xmm, xmm/m128: Encrypt last round AESDEC xmm, xmm/m128: Decrypt one round using equivalent inverse cipher

AESDECLAST xmm, xmm/m128: Decrypt last round using equivalent inverse cipher

Key Manipulation Instructions:

AESIMC xmm, xmm/m128: Inverse mix columns AESKEYGENASST xmm, xmm/m128, imm8: Generate next key from source material as indicated by imm8

Carryless Multiply:

CLMUL XMM, XMM, imm8 Carry less multiplication of 64 bits (as selected by the imm8) out of the two XMM registers returning a full 128 bit result.

Documentation at intel.com

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Sample Code – Encrypt Round (ECB)

mov ECX, \$1 ;; initialize key/round counter mov XMM1, PLAINTEXT ;; load the plaintext to encrypt pxor XMM1, KEYSCHEDULE[\$0]

aesloop:

AESENC XMM1, KEYSCHEDULE[ECX]

inc ECX

cmp ECX, \$0x9

;; 10 rounds in AES128

ja aesloop

AESENCLAST XMM1, KEYSCHEDULE[ECX]

mov CIPHERTEXT, XMM1

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Sample Code – Round Key Generation (128-bit)

AESKEYGEN XMM1, INPUTKEY, 0x0 ;; gen ROUND 0 key movdqa KEYSCHEDULE[0x0], XMM1 ;; store key AESKEYGEN XMM1, XMM1, 0x1 ;; gen the ROUND 1 key movdqa KEYSCHEDULE[0x1], XMM1 ;; store key AESKEYGEN XMM1, XMM1, 0x2 ;; gen the ROUND 2 key

192 & 256 bit key generation are also supported

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Westmere Adds FIT boot to TXT

FIT Boot

Threat:

Unauthorized modification of the BIOS Boot **Functions:**

Measures all regions of the BIOS specified If assets in memory (i.e., secrets set) Verify that BIOS is authorized

If not: Brick

Adds signature-based BIOS verification Scales TXT to large platforms

Security Benefit:

SINIT can gain assurance security-related patches were done. Reduces a threat (i.e., un-authorization of the BIOS) into a denial of service.

SCLEAN

Threat:

Unauthorized modification of BIOS Boot Block exposes assets after a crash

Functions:

Scrubs memory after crash

Security Benefit:

Boot environment has assurance that rogue BIOS cannot access assets

SENTER/ SINIT

Threat:

Subversion of kernel image on "disk" **Functions:**

Deterministic Launch Verified Platform Configuration

Security Benefit:

Untrusted components cannot interfere with MLE's measurement or launch control

STM (SMM Transfer Module) Threat:

Rogue SMI handler provides attack pad **Functions:**

Shim SMI handler with policy engine

Security Benefit:

Kernel can evaluate threat of SMM to the assets

Evaluation of trusted SMM component (STM) is feasible where evaluation of BIOS SMI is not feasible.

Yellow features existed prior to Westmere as part of TXT.

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TXT – What is it

- Trusted eXecution Technology :
 - Works by creating a Measured Launch Environment (MLE)
 - MLE enables accurate HW based checks of TXT-enabled BIOS, hypervisor, or O/S environments via an cryptographically unique identifier for each approved launch-enabled software component.
 - Allows CPU HW check of boot environment or hypervisor launch code signatures against known good ones stored in a secure Trusted Platform Module (TPM) to prevent rogue firmware and BIOS attacks from gaining control of the system.
 - Stops launch of Firmware and Software which does not have the correct prescribed checksum expected.
 - Launch Control Policy tools decide on next system actions
- Westmere adds TXT system runtime firmware measurement
 - Allows BIOS and RAS feature setup to be included in the MLE

Detailed TXT whitepaper on Intel.com (see last foil)

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Acronyms Glossary

Westmere-EP = Efficient Performance = Xeon-5600 series

VR = Voltage Regulator

RC = Resistive Capacitance

TTM = Time to Market

DB = Database

LGA = Land Grid Array (packaging technology)

TXT = Trusted Execution Technology

L3\$ = Level 3 cache (also called LLC for Nehalem, Westmere = Last Level Cache)

XSnp = cross-snoop. A coherency function and filter whereby the uncore knows and checks the subset of on-die core caches that may have copies of a system address.

UnCore = areas of chip which are not the converged client-server CPU core.

CR3 = IA register which allows a context switch when written

IDI = In-Die-Interface. The core-uncore communication interface. Allows low-latency dynamically variable voltage and frequency domain jumps.

VM = Virtual Machine. A software based version of a machine.

VMM = Virtual Machine Monitor. The supervisor of a virtual machine.

WDC = WoodCrest platform. A FSB based Core2[™] Merom / Penryn era platform.

PCU = Power Control Unit

AES = Advanced Encryption Standard

VTx =

Additional References :

AESNI at http://www.intel.com/technology/security/downloads/323587.pdf

AESNI at <u>http://software.intel.com/en-us/articles/intel-advanced-encryption-standard-instructions-aes-ni/</u> Intel Trusted Execution Technology : visit <u>http://www.intel.com/technology/security</u>

